

SCHOTTKY BARRIER DIODE

●Applications

Low current rectification and high speed switching

●Features

Extremely small surface mounting type. (SC-79/SOD523)

Extremely Fast Switching Speed

Extremely Low Forward Voltage 0.5 V (max) @ $I_F = 200$ mA

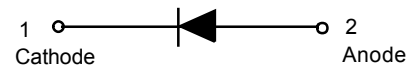
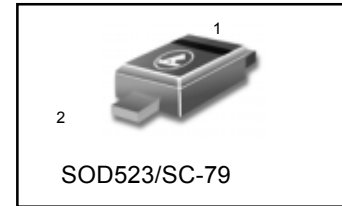
Low Reverse Current

●Construction

Silicon epitaxial planar

- We declare that the material of product compliance with RoHS requirements.

LRB521S-30T1G



DEVICE MARKING AND ORDERING INFORMATION

Device	Marking	Shipping
LRB521S-30T1G	5M	3000/Tape&Reel
LRB521S-30T3G	5M	10000/Tape&Reel

MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$)

Parameter	Symbol	Limits	Unit
DC reverse voltage	V_R	30	V
Mean rectifying current	I_o	200	mA
Peak forward surge current*	I_{FSM}	1	A
Junction temperature	T_j	125	$^\circ\text{C}$
Storage temperature	T_{sg}	-40~+125	$^\circ\text{C}$

*60Hz for 1cycle.

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$)

Parameter	Symbol	Min.	Typ	Max.	Unit	Conditions
Forward voltage	V_F	-	-	0.50	V	$I_F = 200\text{mA}$
Reverse current	I_R	-	-	30	μA	$V_R = 10\text{V}$

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Electrical characteristic curves(Ta=25°C)

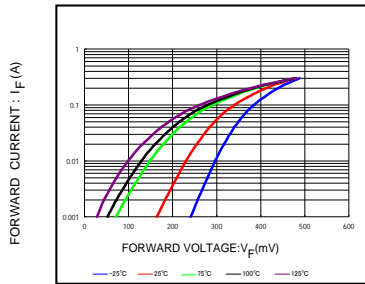


Fig. 1 Forward characteristics

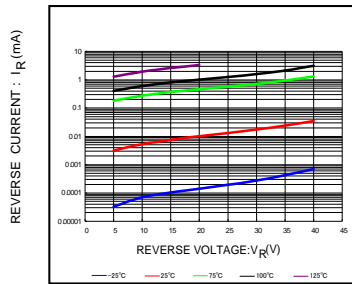


Fig. 2 Reverse characteristics

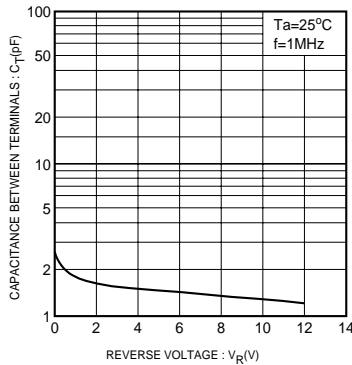
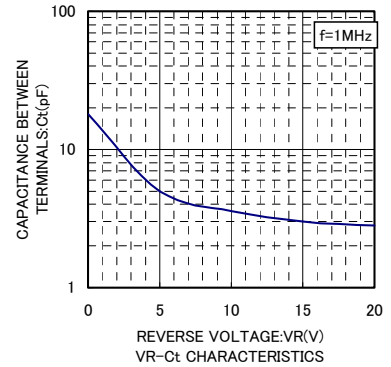


Fig. 3 Capacitance between terminals characteristics

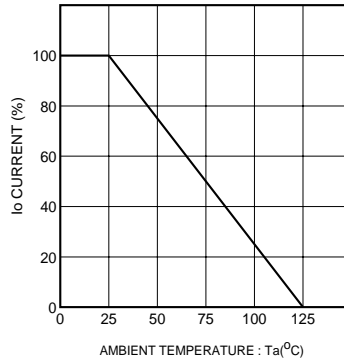
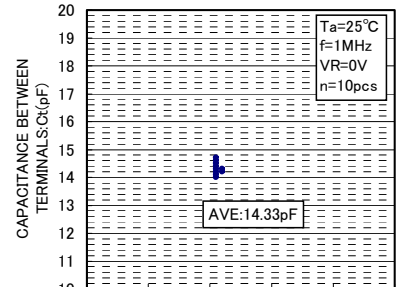
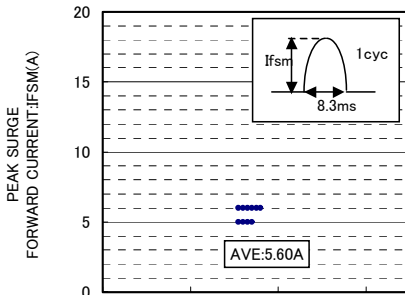


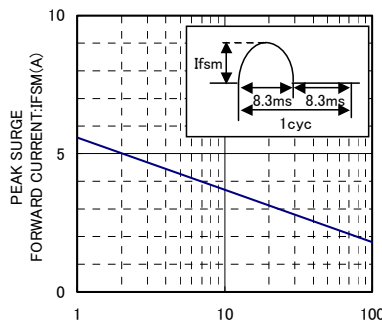
Fig. 4 Derating curve (mounting on glass epoxy PCBs)



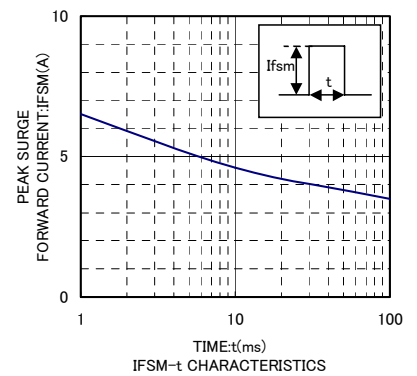
Ct DISPERSION MAP



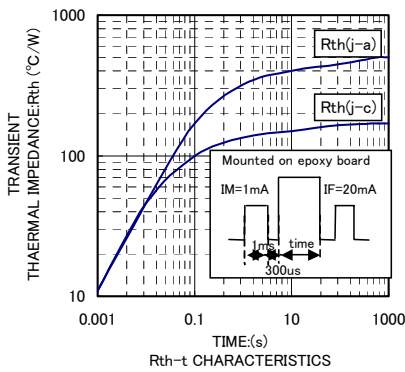
IFSM DISPERSION MAP



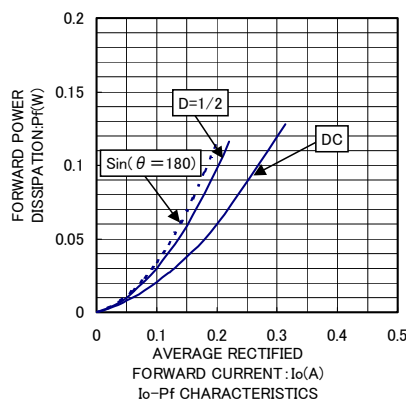
IFSM-CYCLE CHARACTERISTICS



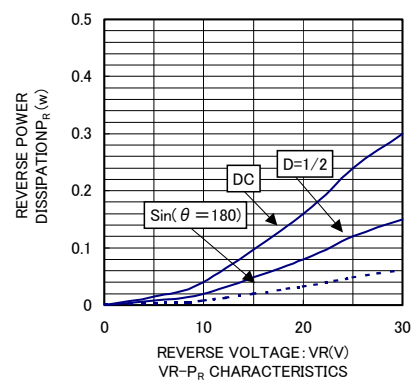
IFSM-t CHARACTERISTICS



Rth-t CHARACTERISTICS



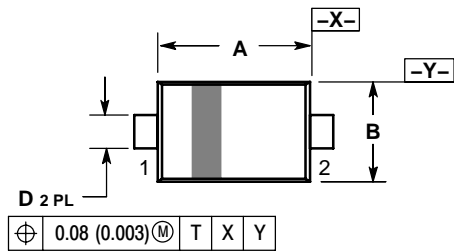
Io-Pf CHARACTERISTICS



VR-PR CHARACTERISTICS

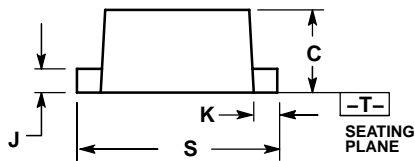
LRB521S-30T1G

SC-79/SOD-523



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.10	1.20	1.30	0.043	0.047	0.051
B	0.70	0.80	0.90	0.028	0.032	0.035
C	0.50	0.60	0.70	0.020	0.024	0.028
D	0.25	0.30	0.35	0.010	0.012	0.014
J	0.07	0.14	0.20	0.0028	0.0055	0.0079
K	0.15	0.20	0.25	0.006	0.008	0.010
S	1.50	1.60	1.70	0.059	0.063	0.067



SOLDERING FOOTPRINT*

